VISCOM
vision technology

S2088BO-II F

Ergonomic Desktop AOI for Wire Bond Inspection

The compact S2088BO-II F system from Viscom is an economical solution for quality control of wire bonds in medium and small series. Its very ergonomic handling makes it a first-class choice for many electronics production companies. Because the S2088BO-II F is compatible with Viscom in-line systems such as the S6053BO-V or S6056BO, it can also be used for creating programs. The completed programs can be transferred quickly and easily.

During inspection, a high-resolution camera captures all bond sites and wires. Damage and misplaced components are also reliably detected. The inspection scope covers wire path, dies, component position and more. It makes no difference whether the bonds are of copper, aluminum or gold, or whether wires or ribbons are involved.

With the S2088BO-II F, Viscom offers a perfect combination of the performance capabilities of their high-end systems and all the advantages of a compact, manually-operated desktop system. Individual support includes a hotline, on-site service and remote diagnosis.

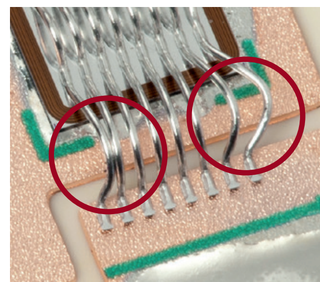
Economical solution in a compact form

Robust inspection with manual loading

Ideal for medium and small series

Proven inspection technology

Impressive high inspection depth



Short circuit (left) and bent wire (right)

Defect detection on multiwire connections and multiple loops

Bond

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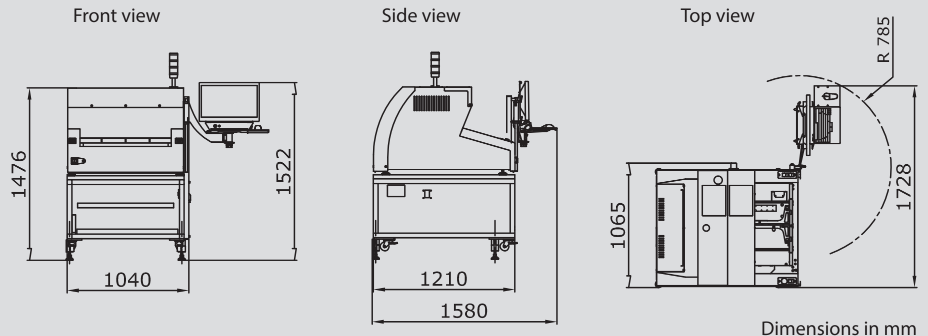
Technical Specifications



		S2088BO-II F
Inspection scope	Bond	Ball bond, wedge bond, wire, die/SMD, ribbon
Camera technology	**Standard configuration 8M1 SRW Bond***	
	Number of modules per machine	1
	Number of cameras	1
	Pixel size	10 µm/pixel
Software	User interface	Viscom EasyPro
	SPC	Viscom SPC (statistical process control), open interface (optional)
	Verification station	Viscom HARAN (integrated into system)
	Remote diagnosis	Viscom SRC (software remote control) (optional)
	Off-line programming	Viscom PST34 (external programming station) (optional)
System computer	Operating system	Windows®
	Processor	Intel® Core™ i7
Substrate handling	Max. substrate size	600 mm x 457 mm (23.6" x 18") (L x W)*
	Substrate thickness	1.0 - 6.0 mm (0.04" - 0.2")
	Width adjustment	Manual
	Substrate clamping	Mechanical clamping
	Upper transport clearance	Up to 35 mm (1.4")
	Lower transport clearance	60 mm (2.4")
Inspection speed		Up to 1000 wire bond connections/min., depending on inspection object characteristics
Other system data	Positioning/handling unit	Synchronous linear motors
	Power requirements	110 - 240 V, 1P/N/PE, 10 A
	Optional equipment	Table, signal lamp
	System dimensions (full equipment)	1040 mm x max. 1899 mm x 1210 mm (40.9" x max. 74.8" x 47.6") (W x H x D)
	Weight (full equipment)	275 kg (606 lbs)

*Other camera technologies and substrate sizes on request

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#Viscom_S2088BO-II F_EN19100003

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